

EE105 – Fall 2015

Microelectronic Devices and Circuits: Basic Semiconductors

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Excellent Reference for Module 2:

Chenming Hu, *Modern Semiconductor Devices for Integrated Circuits*, 2010

downloadable from:

<https://people.eecs.berkeley.edu/~hu/Book-Chapters-and-Lecture-Slides-download.html>

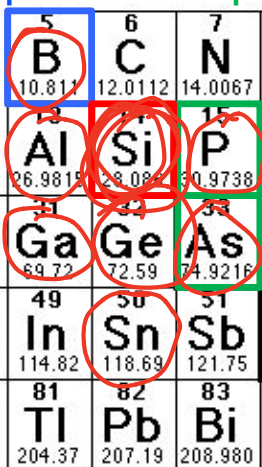


Silicon: Group IV Element

IA	IIA	IIIB	IVB	VB	VIB	VII B	VIII	IB	IIB	IIIA	IVA	VA	VIA	VIIA	GASES
1 H 1.00797	2 He 4.0026														
3 Li 6.939	4 Be 9.0122														
11 Na 22.9898	12 Mg 24.312														
19 K 39.102	20 Ca 40.08	21 Sc 44.956	22 Ti 47.90	23 V 50.942	24 Cr 51.996	25 Mn 54.9380	26 Fe 55.847	27 Co 58.9332	28 Ni 58.71	29 Cu 63.54	30 Zn 65.37	31 Ga 69.72	32 Ge 72.59	33 As 74.9216	34 Se 78.96
37 Rb 85.47	38 Sr 87.62	39 Y 88.905	40 Zr 91.22	41 Nb 92.906	42 Mo 95.94	43 Tc (99)	44 Ru 101.07	45 Rh 102.905	46 Pd 106.4	47 Ag 107.870	48 Cd 112.40	49 In 114.82	50 Sn 118.69	51 Sb 121.75	52 Te 127.60
55 Cs 132.905	56 Ba 137.34	*57 La 138.91	72 Hf 178.49	73 Ta 180.948	74 W 183.85	75 Re 186.2	76 Os 190.2	77 Ir 192.2	78 Pt 195.09	79 Au 196.967	80 Hg 200.59	81 Tl 204.37	82 Pb 207.19	83 Bi 208.980	84 Po (210)
87 Fr (223)	88 Ra (226)	†89 Ac (227)	104 Rf (261)	105 Db (262)	106 Sg (266)	107 Bh (262)	108 Hs (265)	109 Mt (266)	110 ? (271)	111 ? (272)	112 ? (277)				

P-type
dopant

N-type
dopant



Resistivity of Typical Materials

- **Conductors**

- Copper: $1.7 \times 10^{-6} \Omega\text{-cm}$ (or $1.7 \times 10^{-8} \Omega\text{-m}$)
 - Aluminum: $2.8 \times 10^{-6} \Omega\text{-cm}$
- $\rho = \frac{1}{\sigma}$

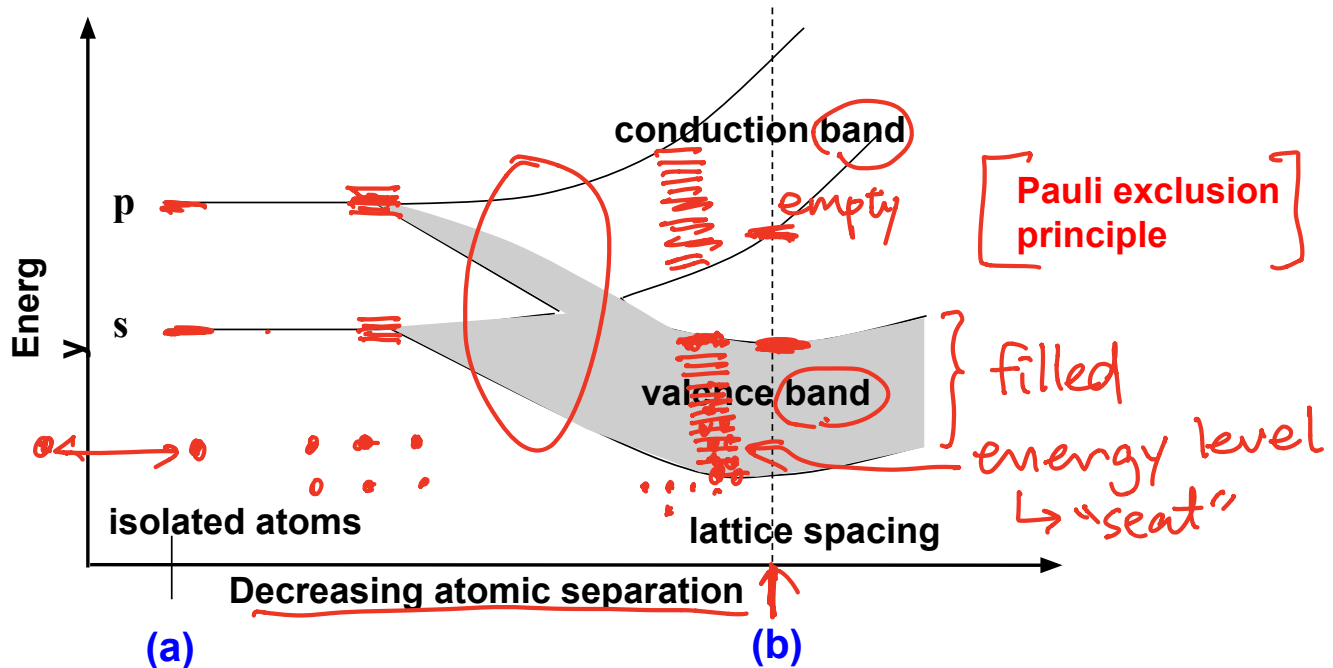
- **Insulators**

- SiO₂: $10^{18} \Omega\text{-cm}$

- **Semiconductor**

- Silicon: 10^{-3} to $10^3 \Omega\text{-cm}$
- A wide range of resistivity,
- Can be controlled by “doping” of impurities or electrical bias

From Atoms to Crystals



- Energy states of Si atom (a) expand into energy bands of Si crystal (b).
- The lower bands are filled and higher bands are empty in a semiconductor.
- The highest filled band is the *valence band*.
- The lowest empty band is the *conduction band*

Energy Band Diagram of Various Materials

$$1.6 \times 10^{-19} \text{ J} = 1 \text{ eV}$$

$$kT = 25 \text{ meV}$$

↑ ↑

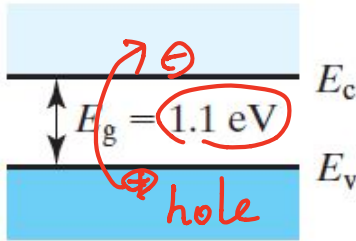
Boltzmann, Kelvin

electron

conduction →

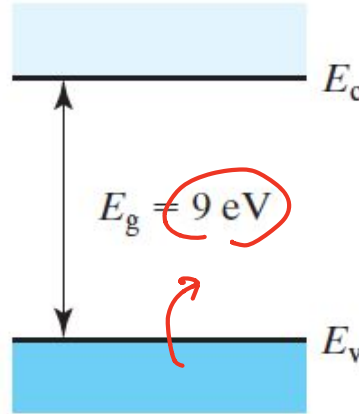
40 kT

valence →



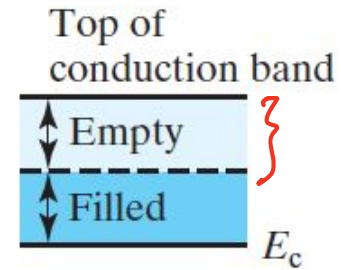
(a) Si, semiconductor

$$E_g \sim 10's \text{ } kT$$



(b) SiO₂, insulator

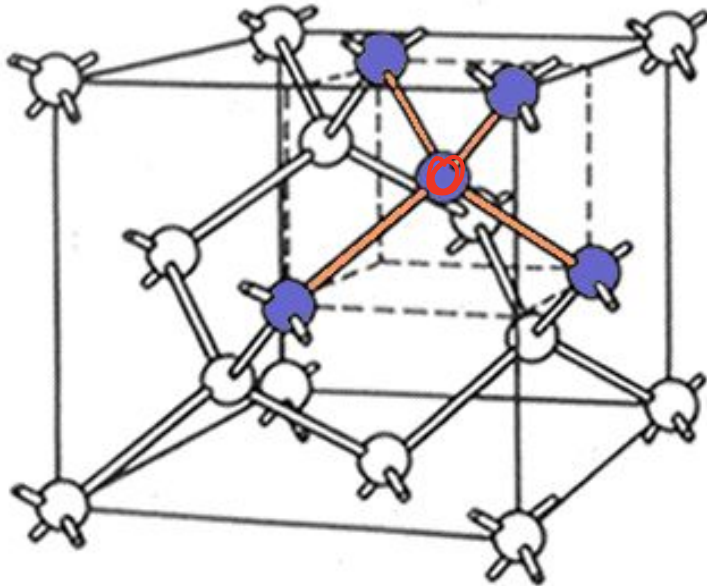
$$E_g \gg 100 \text{ } kT$$



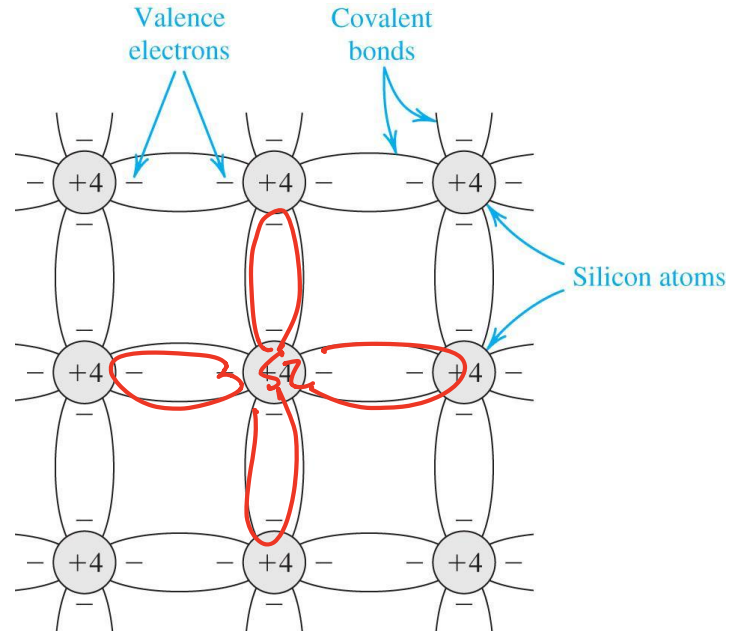
(c) Conductor

Silicon

**Crystalline Structure
(Diamond Cubic)**

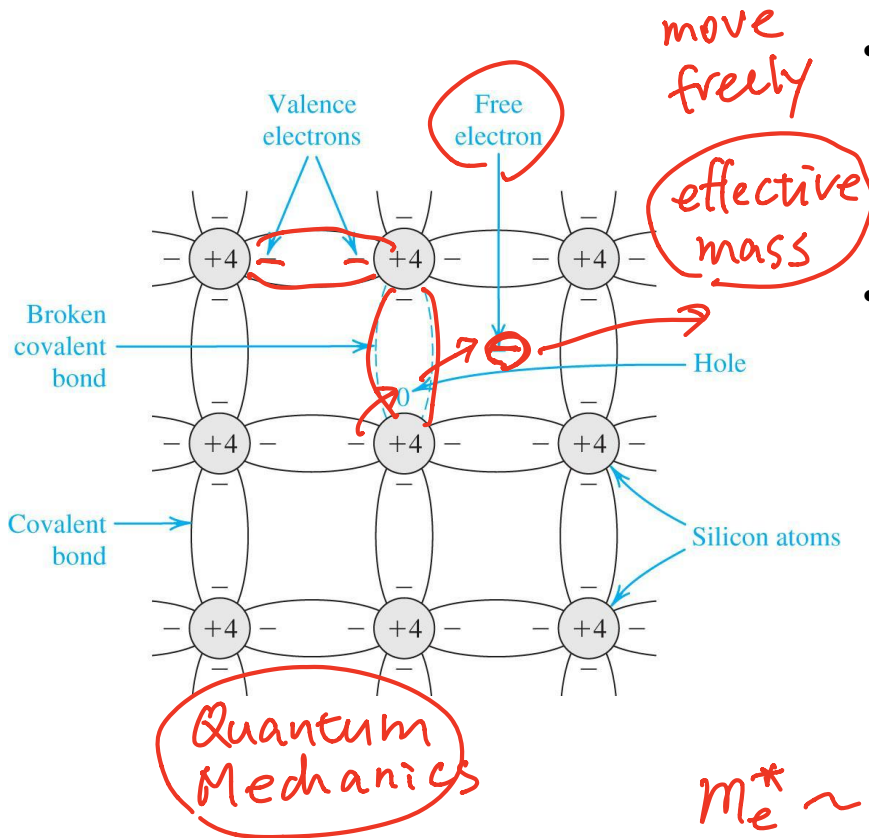


**Schematic Two-Dimensional
Representation**



**At 0 Kelvin, all electrons are
“locked” in covalent bonds
→ Behave like insulator**

Electrons and Holes



- At room temperature, thermal energy breaks some covalent bonds, creating free electrons and “holes”
- Hole: empty space left by electron
 - Hole “moves” as adjacent electron move into its space
 - Treat hole like a positively charged particle

$$m_e^* \sim 0.25 m_e$$

SiC
GaN

Intrinsic Semiconductor

Intrinsic semiconductor

$$n = p = n_i$$

n : electron concentration [cm^{-3}]

p : hole concentration [cm^{-3}]

$$n_i = BT^{\frac{3}{2}} e^{-\frac{E_g}{2kT}}: \text{intrinsic carrier concentration}$$

B : material dependent constant

T : temperature in Kelvin

E_g : bandgap energy (=1.12 eV for Si)

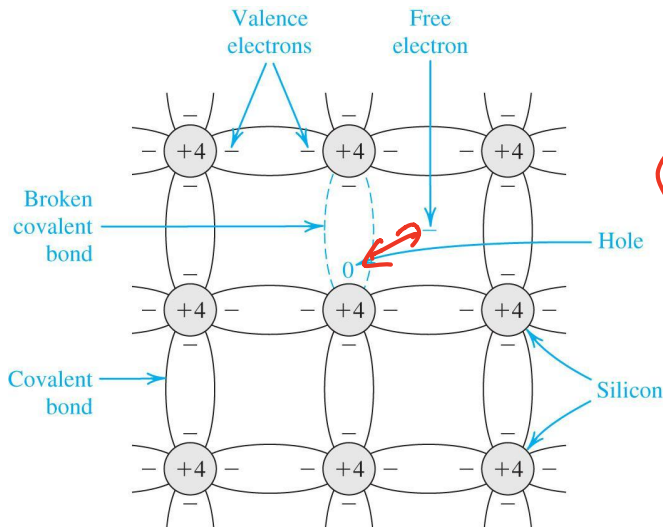
k : Boltzmann's constant = 8.62×10^{-5} eV/K

At room temperature ($T = 300\text{K}$)

$$n_i = 1.5 \times 10^{10} [\text{cm}^{-3}]$$

Note: There are 5×10^{22} atoms/ cm^3 , so the number of free electrons and holes are very small

In general, $np = n_i^2$



$$\frac{n_i}{[Si]} = 10^{-12}$$

B C 5
Si P
Ga As

N-Type Semiconductor

Negative

Electron concentration can be greatly increased by replacing some Si atoms with P (phosphorus) or As (Arsenic), which have 5 shell electrons (one more than Si).

P or As are called "donors"

$n_n = N_D$ (donor impurity concentration)

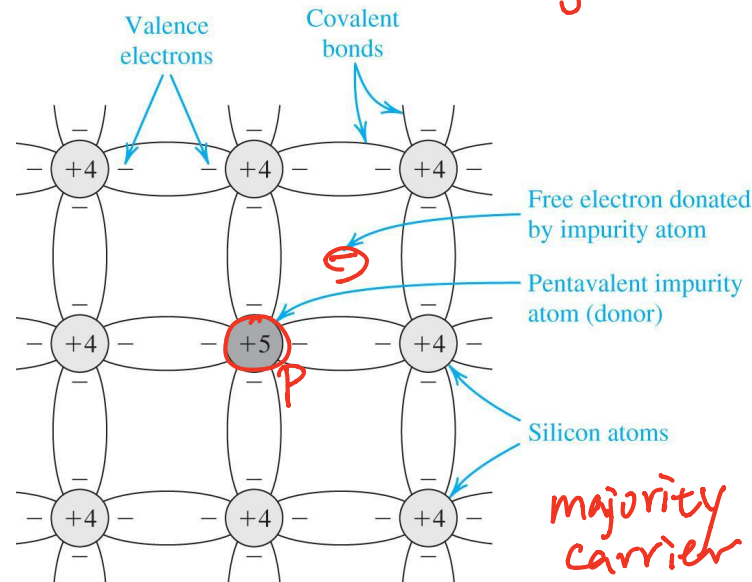
$$p_n = \frac{n_i^2}{N_D} \text{ where } n_i = 1.5 \times 10^{10} \text{ [cm}^{-3}\text{]}$$

Subscript n refers to n-type semiconductor (n stands for "negative", referring to the charge carried by electrons)

In n-type semiconductor, $n_n \gg n_i \gg p_n$

e.g., $N_D = 10^{17} \text{ cm}^{-3}$, $n_n = 10^{17}$, $p_n = 2.2 \times 10^3$

Electrons are "majority" carriers, holes are "minority" carriers



$[P] \sim 10^{15} \sim 10^{19} \frac{1}{\text{cm}^3}$

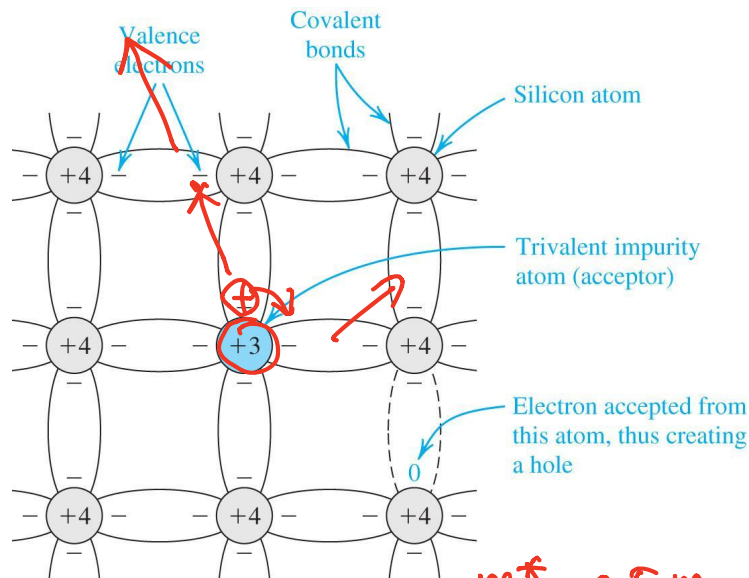
$n \cdot p = n_i^2$ $n_i = 10^{10} \frac{1}{\text{cm}^3}$

Mass Action Law $n \approx 10^{17}$

Minority $\rightarrow p = 10^3$

P-Type Semiconductor

Positive



$$np = n_i^2$$

$$P = 10^{17} \leftarrow$$

$$n \approx 10^3$$

$$m_h^* = 0.5 m_e$$

Hole concentration can be greatly increased by replacing some Si atoms with B (boron), which has 3 shell electrons (one less than Si).

B is called "acceptors"

$p_p = N_A$ (acceptor impurity concentration)

$$n_p = \frac{n_i^2}{N_A} \text{ where } n_i = 1.5 \times 10^{10} \text{ [cm}^{-3}\text{]}$$

The subscript p refers to p-type semiconductor (p stands for "positive", referring to the charge carried by holes)

In p-type semiconductor, $p_p \gg n_i \gg n_p$

e.g., $N_A = 10^{17} \text{ cm}^{-3}$, $p_p = 10^{17}$, $n_p = 2.2 \times 10^3$

Holes are "majority" carriers, electrons are "minority" carriers

How Electron (or Hole) Move

$$\frac{1}{2}mv^2 = kT$$

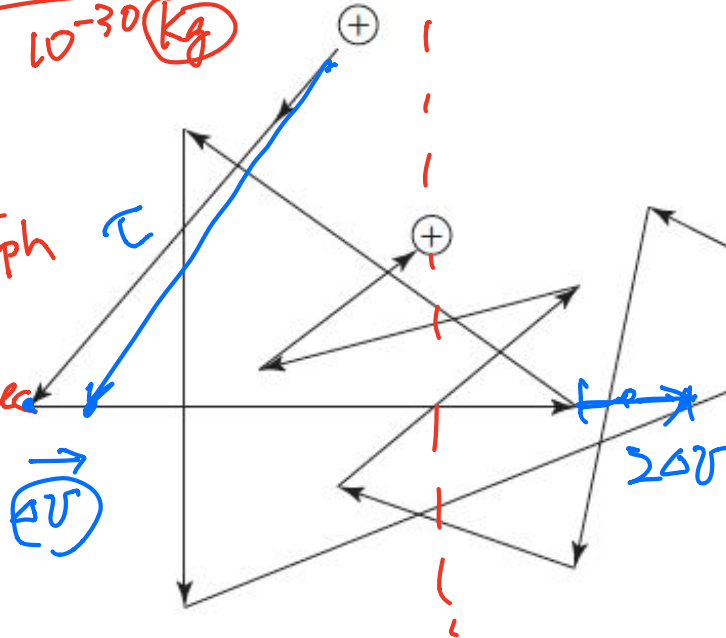
$$v^2 = \frac{25 \times 10^3 \times 1.6 \times 10^{-19} \text{ J} \times 2}{10^{-30} \text{ (kg)}} = \frac{100 \times 10^{-22}}{10^{-30}} = 10^{10}$$

$$v = 10^5 \text{ m/sec}$$

$$= 10^7 \text{ cm/sec}$$

$$\rightarrow 200,000 \text{ mph}$$

$$c = 3 \times 10^{10} \text{ cm/sec}$$



$$mv = F \cdot \Delta t$$

↑
average velocity

$$mv = (qE) \tau$$

$$v = \left(\frac{q\tau}{m} \right) E$$

τ = mean free time bt collision

$$v = \mu E$$

↑

No Electric Field

mobility

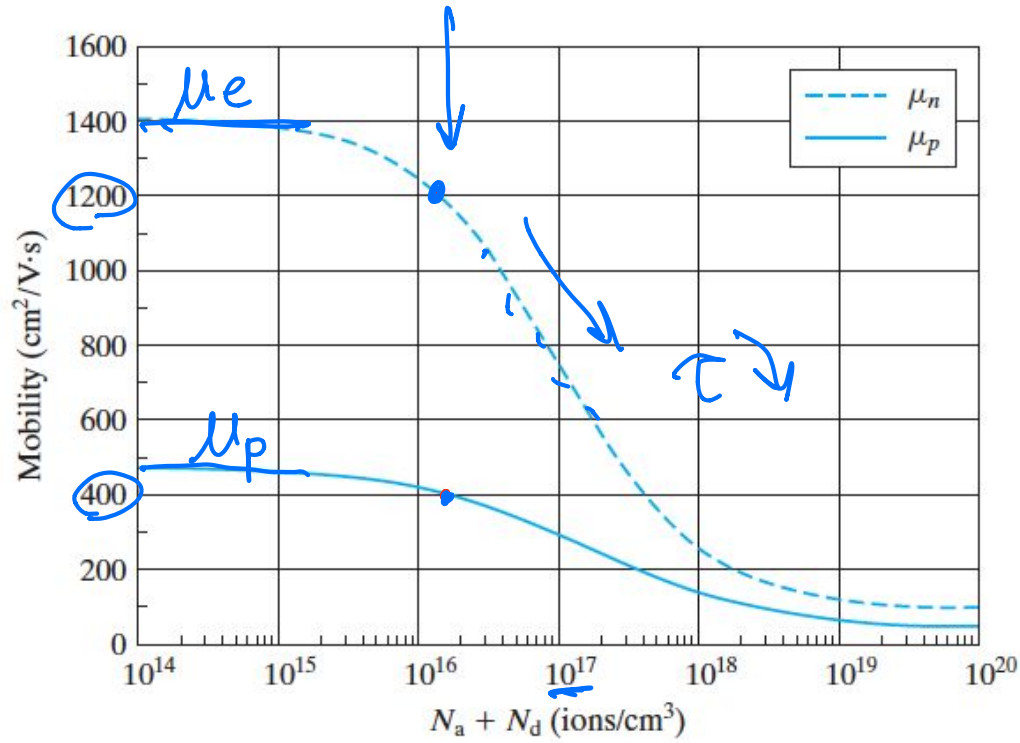


Mobility of Common Semiconductors

TABLE 2-1 • Electron and hole mobilities at room temperature of selected lightly doped semiconductors.

		Si	Ge	GaAs	InAs
μ_n (cm ² /V·s)	3x	1400	3900	8500	30,000
μ_p (cm ² /V·s)	1x	470	1900	400	500

Mobility vs Dopant Concentration



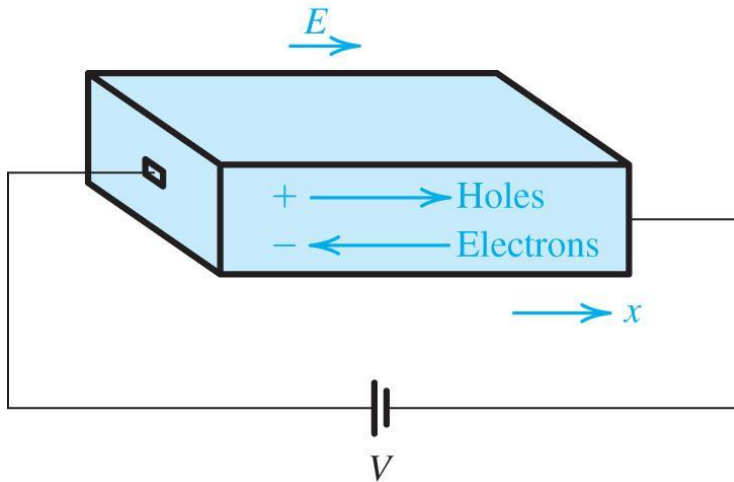
$$\mu = \frac{q\tau}{m}$$

→ doping $\mu \downarrow$

Current: Movement of Charged Particles (Electrons and Holes)

v_{th} (thermal velocity)
 ΔV (drift velocity)
 τ : mean free time
 $m \cdot \Delta V = \Delta P = F \cdot \tau = (q \cdot E) \cdot \tau \Rightarrow \Delta V = \left(\frac{q \tau}{m} \right) \cdot E = \mu E$
 μ : mobility
 τ : function of temp, impurity, conc.
 $v = v_{th} + \Delta V$
 $10^7 \frac{cm}{sec}$
 E (Electric field)
 J_n (Current density)
 $v \cdot 1 sec$
 $\frac{1}{2} m v^2 = kT$
 $I \times I \times (v \times 1 sec) \times n$
 $J = n \cdot q \cdot v$
 $= n \cdot q \cdot \mu E$
 $\frac{I}{Area} = \sigma E$
 $= \frac{1}{\rho} E$

Current in Semiconductor (1): Drift Current



When an electrical field, E , is applied, holes move in the direction of E , while electrons move opposite to E :

$$\begin{cases} v_{p\text{-drift}} = \mu_p E, & \mu_p : \text{hole mobility} \\ v_{n\text{-drift}} = -\mu_n E, & \mu_n : \text{electron mobility} \end{cases}$$

In intrinsic Si, $\mu_n = 1350 \text{ cm}^2 / \text{V} \cdot \text{s}$

$\mu_p = 480 \text{ cm}^2 / \text{V} \cdot \text{s}$ (Note: $\mu_n \approx 2.5\mu_p$)

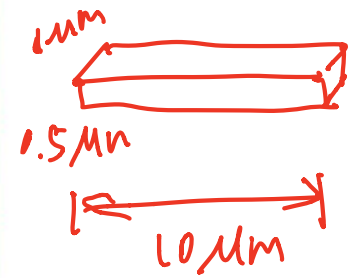
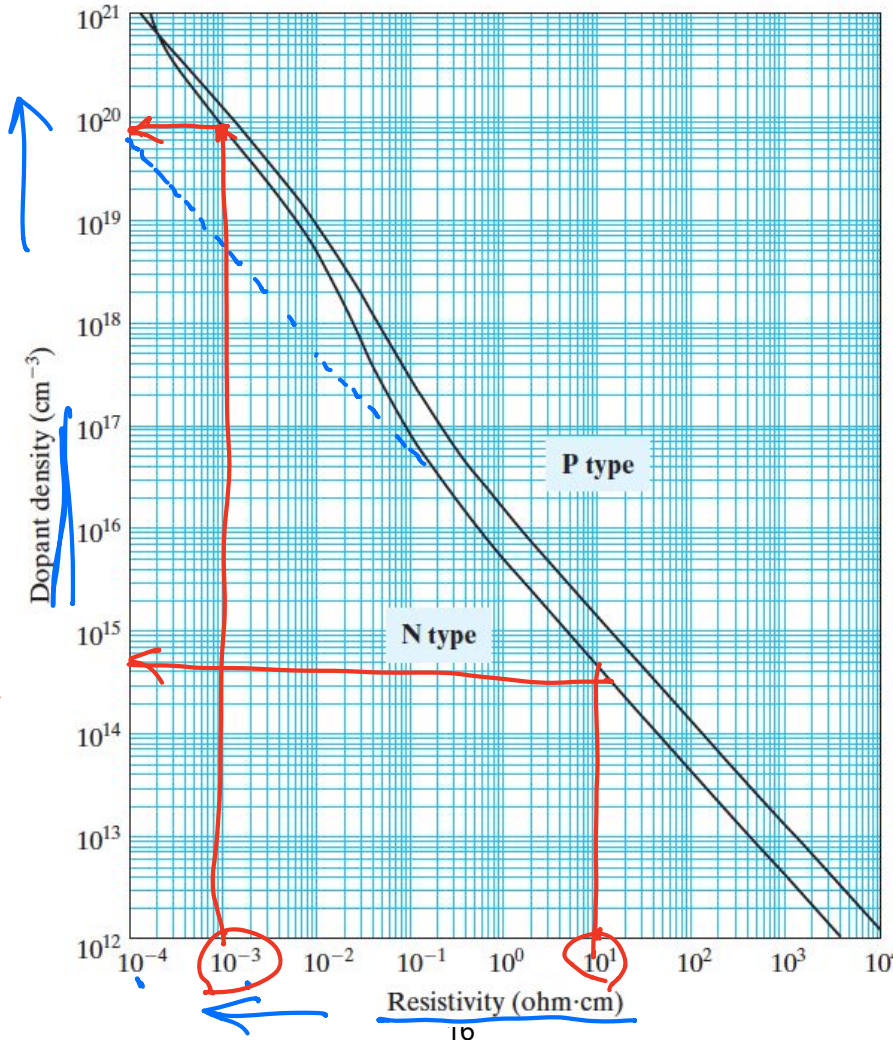
Current density, J [A/cm^2]

$$J = \underbrace{qp v_{p\text{-drift}}}_{\text{hole current}} + \underbrace{qn v_{n\text{-drift}}}_{\text{electron current}} = \underbrace{q(p\mu_p + n\mu_n)}_{\sigma} E = \sigma E$$

where $\sigma = q(p\mu_p + n\mu_n)$ is conductivity [S/cm]

Resistivity $\rho = \frac{1}{\sigma}$ [$\Omega\text{-cm}$]

Resistivity vs Dopant Concentration



$$R = \rho \cdot \frac{l}{A}$$

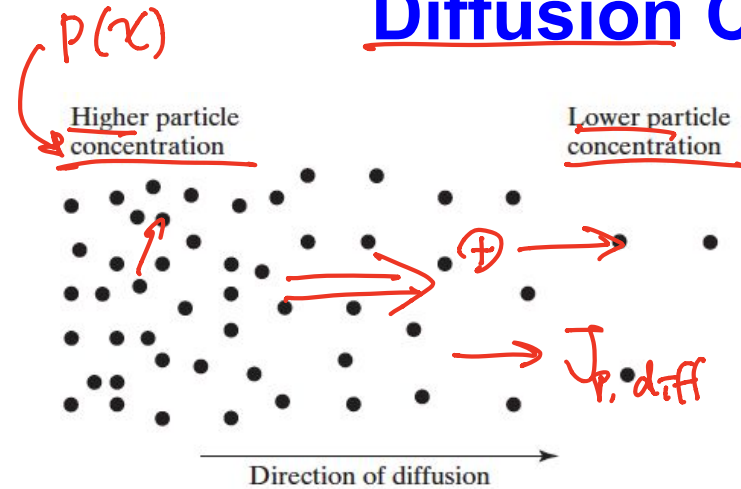
$$\frac{1}{nq\mu_n + pq\mu_p}$$

$$\rho = \frac{1}{\sigma}$$

n
or p

$N_D + N_A$

Current in Semiconductor (2): Diffusion Current - Holes



- If hole distribution is non-uniform, holes will move from high to low concentration areas

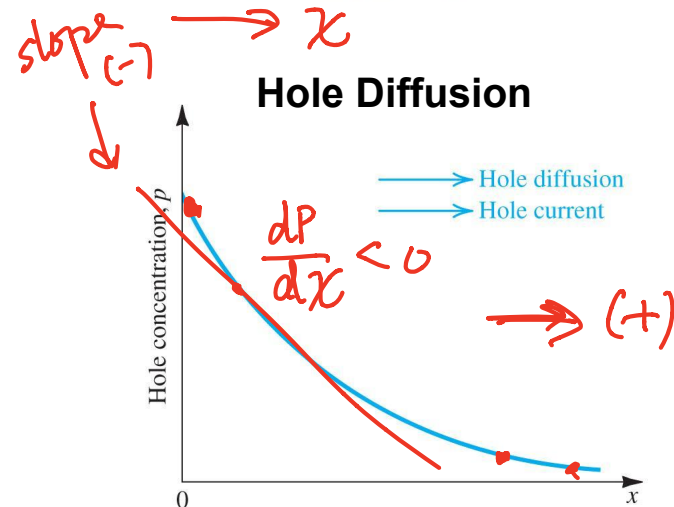
- Flux \propto [conc. gradient] $-\frac{dp(x)}{dx}$

- Current flows since holes carry charge:

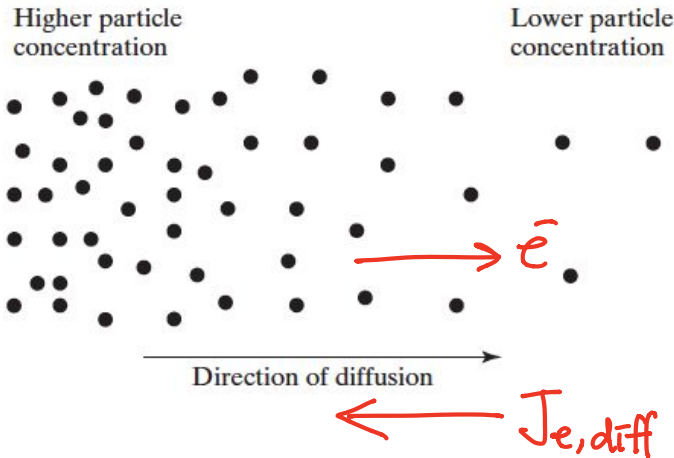
$$J_{p-diff} = qD_p \left(-\frac{dp(x)}{dx} \right)$$

D_p : hole diffusion coef. [cm^2/s]

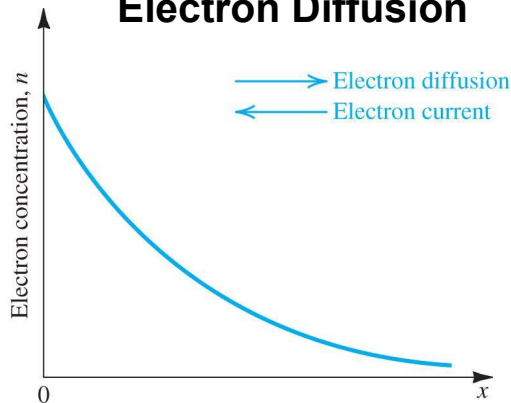
- Note: since hole carries positive charge, hole diffusion and hole current are in the same direction



Current in Semiconductor (2): Diffusion Current - Electrons



Electron Diffusion



- Similarly, electron diffusion also causes current to flow, but in opposite direction since electron carries negative charge

$$J_{n-diff} = \underbrace{(-q)}_{\text{electron}} D_n \left(- \underbrace{\frac{dn(x)}{dx}}_{\text{flux}} \right)$$

$$= \underbrace{q D_n \frac{dn(x)}{dx}}$$

D_n : electron diffusion coef. [cm^2/s]

J_{n-diff} : [A/cm^2]

- In Si,

– $D_n = \underline{35 \text{ cm}^2/\text{s}}$

– $D_p = \underline{12 \text{ cm}^2/\text{s}}$

$$\frac{\mu_n}{\mu_p} \approx 3$$

$$\frac{D_n}{D_p} \sim 3$$

Einstein Relationship

$$\frac{D_n}{\mu_n} = \frac{D_n}{\mu_n} = V_T = \frac{kT}{q}$$

25 mV

V_T : Thermal voltage

At room temperature, $V_T = 26$ mV

$$E = \left[\frac{V}{cm} \right]$$

$$\phi = [V]$$

$$\mu_n = \frac{D_n}{V_T} = 35 \times 40 = 1400$$

$$\frac{d e^{f(x)}}{dx} = \frac{d f(x)}{dx} \cdot e^{f(x)}$$

$$J_n = n q \mu_n \left(-\frac{d\phi}{dx} \right) + q D_n \cdot n \left(\frac{d\phi}{dx} \right) \frac{q}{kT} = 0$$

$$D_n \cdot \left(\frac{q}{kT} \right) = \mu_n \Rightarrow \frac{D_n}{\mu_n} = \frac{kT}{q} = V_T = 25 \text{ mV}$$

$$J_n = \underbrace{n q \mu_n E}_{\text{drift}} + \underbrace{q D_n \frac{dn}{dx}}_{\text{diffusion}}$$

In equilibrium $J_n = 0$

$$E = -\frac{d\phi}{dx} \quad \phi = \text{electrostatic potential}$$

n follows Boltzmann dist

$$n = n_0 e^{\frac{q\phi}{kT}} = n_0 e^{-\frac{(-q)\phi}{kT}}$$

$$\frac{dn}{dx} = n_0 \left(\frac{q}{kT} \right) \frac{d\phi}{dx} \cdot e^{\frac{q\phi}{kT}} = n \frac{d\phi}{dx} \frac{q}{kT}$$

$$\frac{D_n}{\mu_n} = \frac{kT}{q} = V_T = 25 \text{ mV}$$